

### 57mm (2.3INCH) SINGLE DIGIT NUMERIC DISPLAY

Part Number: SC23-11GWA

Green

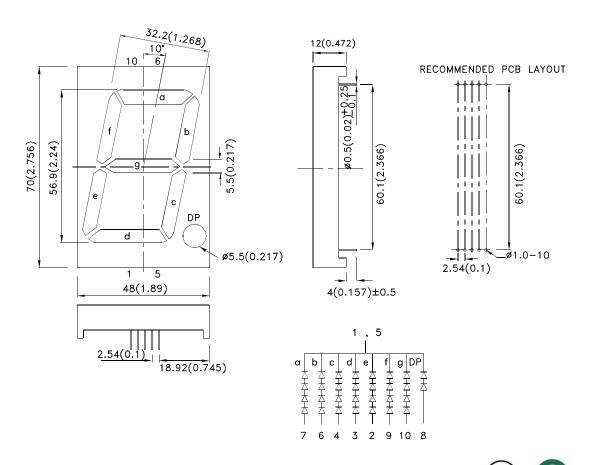
#### **Features**

- 2.3 inch digit height.
- Low current operation.
- Excellent character appearance.
- High light output.
- Easy mounting on P.C. boards or sockets.
- Multicolor available.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

### Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

### **Package Dimensions& Internal Circuit Diagram**







2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAN0658 REV NO: V.1A DATE: JUN/24/2013 PAGE: 1 OF 7

APPROVED: WYNEC CHECKED: Joe Lee DRAWN: D.N.Huang ERP: 1301000819

### **Selection Guide**

Part No.	Dice	Lens Type	lv (ucd) [1] @ 10mA		Description
			Min.	Тур.	2000.1611011
SC23-11GWA	Green (GaP)	White Diffused	31000	65000	Common Cathode. Rt. Hand Decimal
			*9000	*20000	

#### Notes:

- Luminous intensity/ luminous Flux: +/-15%.
   \* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage (DP)	Green	8.8 (4.4)	10.0 (5.0)	V	I=20mA
lR	Reverse Current (Per Chip)	Green		10 (10)	uA	VR=5V (VR=5V)

- 1.Wavelength: +/-1nm.
  2. Forward Voltage: +/-0.1V.
  3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

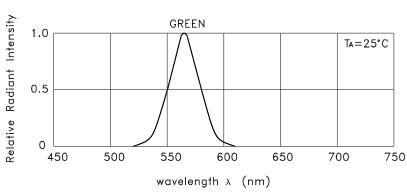
### Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation (DP)	250 (125)	mW	
DC Forward Current (DP)	25 (25)	mA	
Peak Forward Current [1] (DP)	140 (140)	mA	
Reverse Voltage (Per Chip)	5 (5)	V	
Operating / Storage Temperature	-40°C To +85°C		
Lead Solder Temperature[2]	260°C For 3-5 Seconds		

#### Notes:

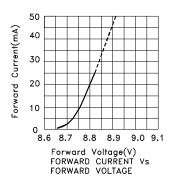
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.

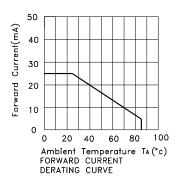
SPEC NO: DSAN0658 **REV NO: V.1A** DATE: JUN/24/2013 PAGE: 2 OF 7 APPROVED: WYNEC **CHECKED:** Joe Lee ERP: 1301000819 DRAWN: D.N.Huang

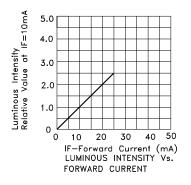


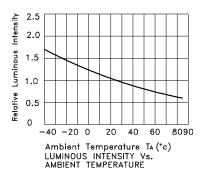
RELATIVE INTENSITY Vs. WAVELENGTH

### Green SC23-11GWA



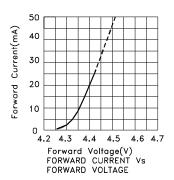


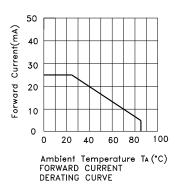


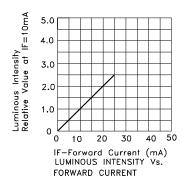


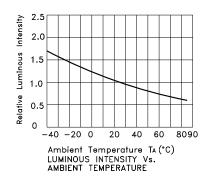
SPEC NO: DSAN0658 REV NO: V.1A DATE: JUN/24/2013 PAGE: 3 OF 7

APPROVED: WYNEC CHECKED: Joe Lee DRAWN: D.N.Huang ERP: 1301000819

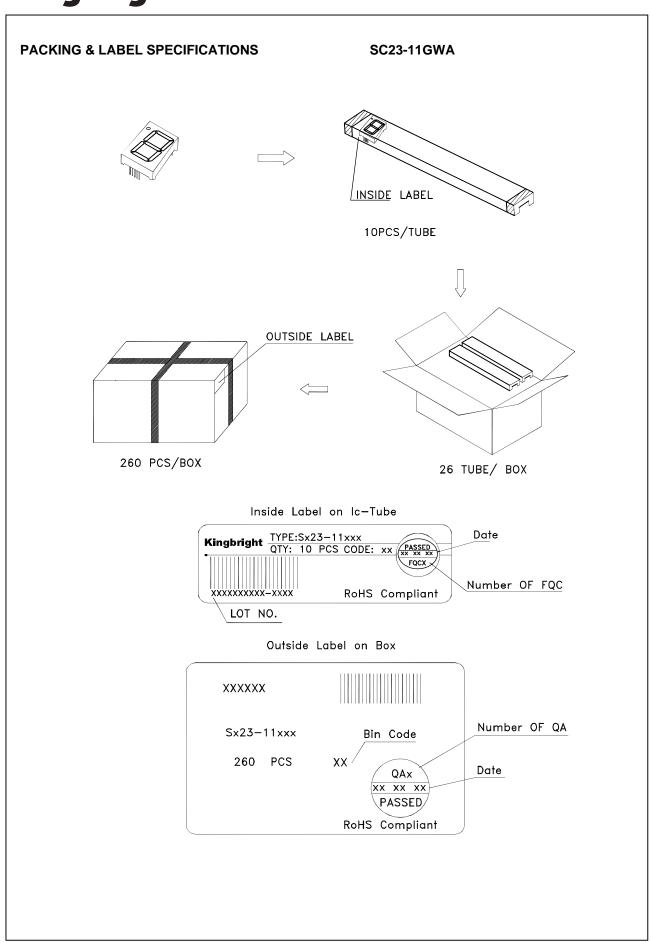








SPEC NO: DSAN0658 REV NO: V.1A DATE: JUN/24/2013 PAGE: 4 OF 7
APPROVED: WYNEC CHECKED: Joe Lee DRAWN: D.N.Huang ERP: 1301000819

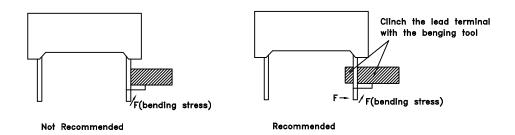


SPEC NO: DSAN0658 APPROVED: WYNEC REV NO: V.1A CHECKED: Joe Lee DATE: JUN/24/2013 DRAWN: D.N.Huang PAGE: 5 OF 7 ERP: 1301000819

### THROUGH HOLE DISPLAY MOUNTING METHOD

### Lead Forming

Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

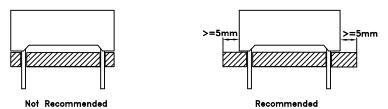


### Installation

- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.

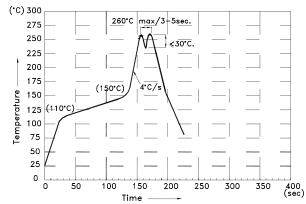


SPEC NO: DSAN0658 REV NO: V.1A DATE: JUN/24/2013 PAGE: 6 OF 7

APPROVED: WYNEC CHECKED: Joe Lee DRAWN: D.N.Huang ERP: 1301000819

### DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



#### NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top-surface temperature should be kept below  $105^{\circ}C$
- 5.No more than once.

### Soldering General Notes:

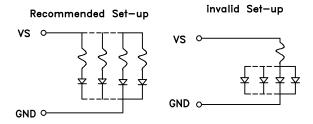
- 1. Through—hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

#### **CLEANING**

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

### CIRCUIT DESIGN NOTES

- 1.Protective current—limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



All design applications should refer to Kingbright application notes available at <a href="http://www.KingbrightUSA.com/ApplicationNotes">http://www.KingbrightUSA.com/ApplicationNotes</a>

SPEC NO: DSAN0658 REV NO: V.1A DATE: JUN/24/2013 PAGE: 7 OF 7

APPROVED: WYNEC CHECKED: Joe Lee DRAWN: D.N.Huang ERP: 1301000819